This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-6 (Canceled).

Claim 7. (Original) A method of making a chip device, the method comprising:

providing a leadframe that includes leads;

providing a die that includes a metallized backside;

coupling the die to the leadframe; and

encapsulating the die with a body such that the metallized backside of the die is adjacent a window defined within the body.

Claim 8. (Original) A method in accordance with claim 7 further comprising configuring the plurality of leads.

Claim 9. (Original) A method in accordance with claim 8 further comprising removing dambars from the leadframe, removing mold flashes and resins from the leads, and solder plating the leads.

Claim 10. (Original) A method in accordance with claim 7 further comprising marking the body on a surface opposite the window.

Claim 11. (Original) A method in accordance with claim 10 wherein the marking is performed with a laser.

Claim 12. (Original) A method in accordance with claim 10 wherein the marking is performed with ink.

Claim 13. (Original) A method in accordance with claim 7 wherein the leadframe is provided with preplated leads.

Claim 14. (Original) A method in accordance with claim 7 wherein the leadframe is provided with preformed leads.

Claim 15. (Original) A method in accordance with claim 7 wherein the leadframe is provided with preplated leads and preformed leads.

Claim 16. (Original) A method in accordance with claim 7 wherein the die is coupled to the leadframe die attach pad and post via solder bumps, and wherein the solder bumps are re-flowed.

Claim 17. (Original) A method in accordance with claim 7 wherein the leadframe is provided with two die attach pads and posts, and the method further comprises providing two dies that each include a metallized back side, and coupling the first of the two dies to a first die attach pad and post, coupling a second of the two dies to a second die attach pad and post.

Claim 18. (New) A method comprising:

providing a leadframe that includes leads;

providing a semiconductor die that includes a backside;

mounting the semiconductor die to the leadframe; and

encapsulating the semiconductor die and at least a portion of the leadframe with a molding compound having a window and an exterior surface, wherein the backside of the semiconductor die is exposed through the window of the molding compound and wherein the backside is substantially flush with the exterior surface of the molding compound.

Claim 19. (New) The method of claim 18 wherein the semiconductor die comprises a power transistor.

Claim 20. (New) The method of claim 18 further comprising:

mounting a second semiconductor die including a second backside to the leadframe, wherein second backside is exposed through a second window in the molding compound.

Claim 21. (New) The method of claim 18 wherein mounting the semiconductor die to the leadframe includes using solder to mount the semiconductor die to the leadframe.

Claim 22. (New) The method of claim 18 wherein the semiconductor die comprises source and gate terminals at a side opposite the metallized backside.

Claim 23. (New) The method of claim 18 wherein the leadframe is pre-plated.

Claim 24. (New) The method of claim 18 wherein ends of the leads are co-planar with the backside of the semiconductor die.

Claim 25. (New) The method of claim 18 wherein the backside of the semiconductor die is metallized.